

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Akihiko ENDO et al.

Serial No : Not Yet Assigned (National Stage of PCT/JP2004/013067)

I.A. Filed : September 8, 2004

For : BONDED WAFER AND ITS MANUFACTURING METHOD

PRELIMINARY AMENDMENT

Commissioner of Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop _____
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

Prior to calculation of filing fees and the examination of the above-identified patent application on the merits, the Examiner is respectfully requested to amend the claims as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.